# DSC7101

### Silicon NPN epitaxial planar type

For low frequency amplification Complementary to DSA7101

#### Features

- Low collector-emitter saturation voltage  $V_{CE(sat)}$
- Halogen-free / RoHS compliant
- (EU RoHS / UL-94 V-0 / MSL: Level 1 compliant)

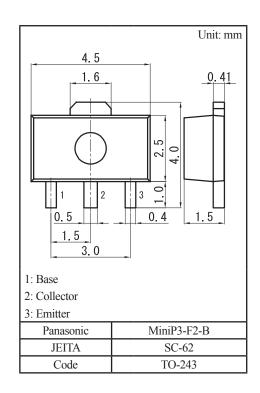
#### Marking Symbol: 5C

#### Packaging

DSC7101×0L Embossed type (Thermo-compression sealing): 1 000 pcs / reel (standard)

#### Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	V <sub>CBO</sub>	80	V
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	V <sub>CEO</sub> 80	
Emitter-base voltage (Collector open)	V <sub>EBO</sub>	5	V
Collector current	I <sub>C</sub>	0.5	А
Peak collector current	I <sub>CP</sub>	1	А
Collector power dissipation	P <sub>C</sub>	1	W
Junction temperature	Tj	150	°C
Operating ambient temperature	T <sub>opr</sub>	-40 to +85	°C
Storage temperature	T <sub>stg</sub>	-55 to +150	°C



Note) Printed circuit board: Copper foil area of 1 cm<sup>2</sup> or more, and the board thickness of 1.7 mm for the collector portion

Absolute maximum rating without heat sink for  $P_C$  is 0.5 W

#### Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V <sub>CBO</sub>	$I_{\rm C} = 10 \ \mu {\rm A}, I_{\rm E} = 0$	80			V
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	$I_{\rm C} = 100 \ \mu A, I_{\rm B} = 0$	80			V
Emitter-base voltage (Collector open)	V <sub>EBO</sub>	$I_{\rm E} = 10 \ \mu {\rm A}, I_{\rm C} = 0$	5			V
Collector-base cutoff current (Emitter open)	I <sub>CBO</sub>	$V_{CB} = 20 \text{ V}, I_E = 0$			0.1	μΑ
Forward current transfer ratio *1	h <sub>FE1</sub> *2	$V_{CE} = 10 \text{ V}, I_C = 150 \text{ mA}$	130		330	
	h <sub>FE2</sub>	$V_{CE} = 5 \text{ V}, I_C = 500 \text{ mA}$	50			
Collector-emitter saturation voltage *1	V <sub>CE(sat)</sub>	$I_{\rm C} = 300 \text{ mA}, I_{\rm B} = 30 \text{ mA}$		0.15	0.4	V
Base-emitter saturation voltage *1	V <sub>BE(sat)</sub>	$I_{\rm C} = 300 \text{ mA}, I_{\rm B} = 30 \text{ mA}$		0.85	1.2	V
Transition frequency	f <sub>T</sub>	$V_{CE} = 10 \text{ V}, I_C = 50 \text{ mA}$		150		MHz
Collector output capacitance (Common base, input open circuited)	C <sub>ob</sub>	$V_{CB} = 10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$		7	20	pF

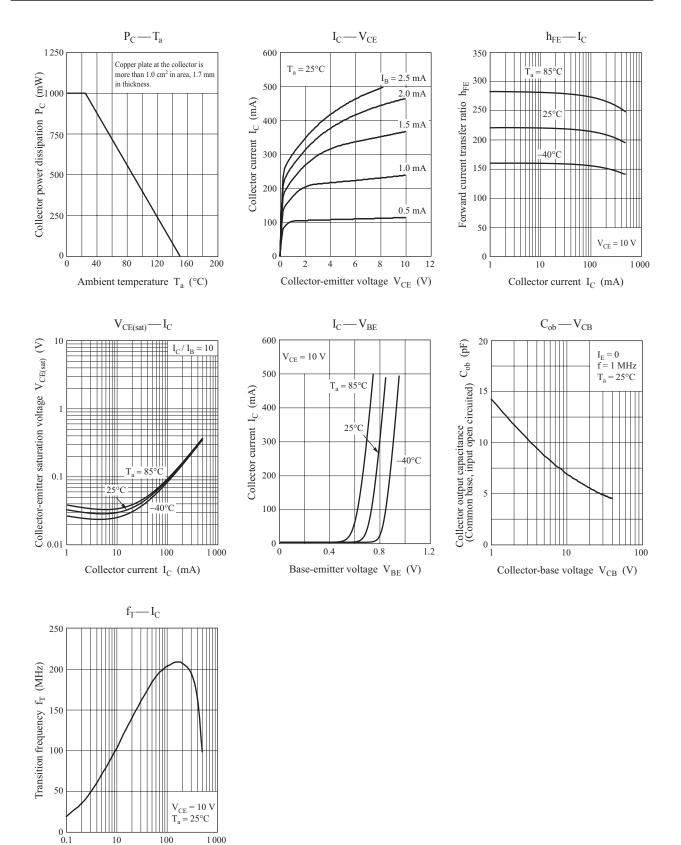
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

2. \*1: Pulse measurement \*2: Rank classification

2. Rank classification						
Code	R	S	0			
Rank	R	S	No-rank			
$h_{FE1}$	130 to 220	185 to 330	130 to 330			
Marking Symbol	5CR	5CS	5C			

Product of no-rank is not classified and have no marking symbol for rank.

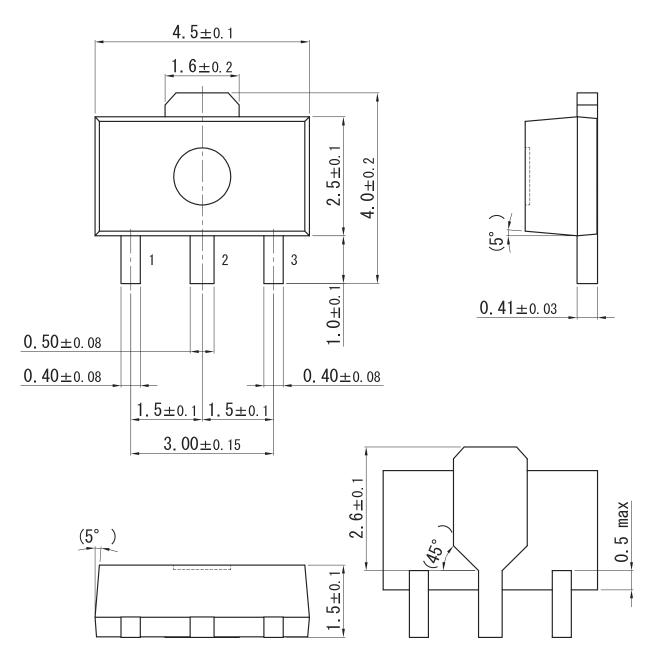
## **Panasonic**



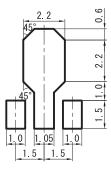
Collector current  $I_C$  (mA)

MiniP3-F2-B

Unit: mm



Land Pattern (Reference) (Unit: mm)



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